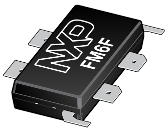


SOT2005-1

FM6F, flange mount package, 6 terminals, 20.4 mm x 9.8 mm x 4.26 mm body

19 June 2019

Package information

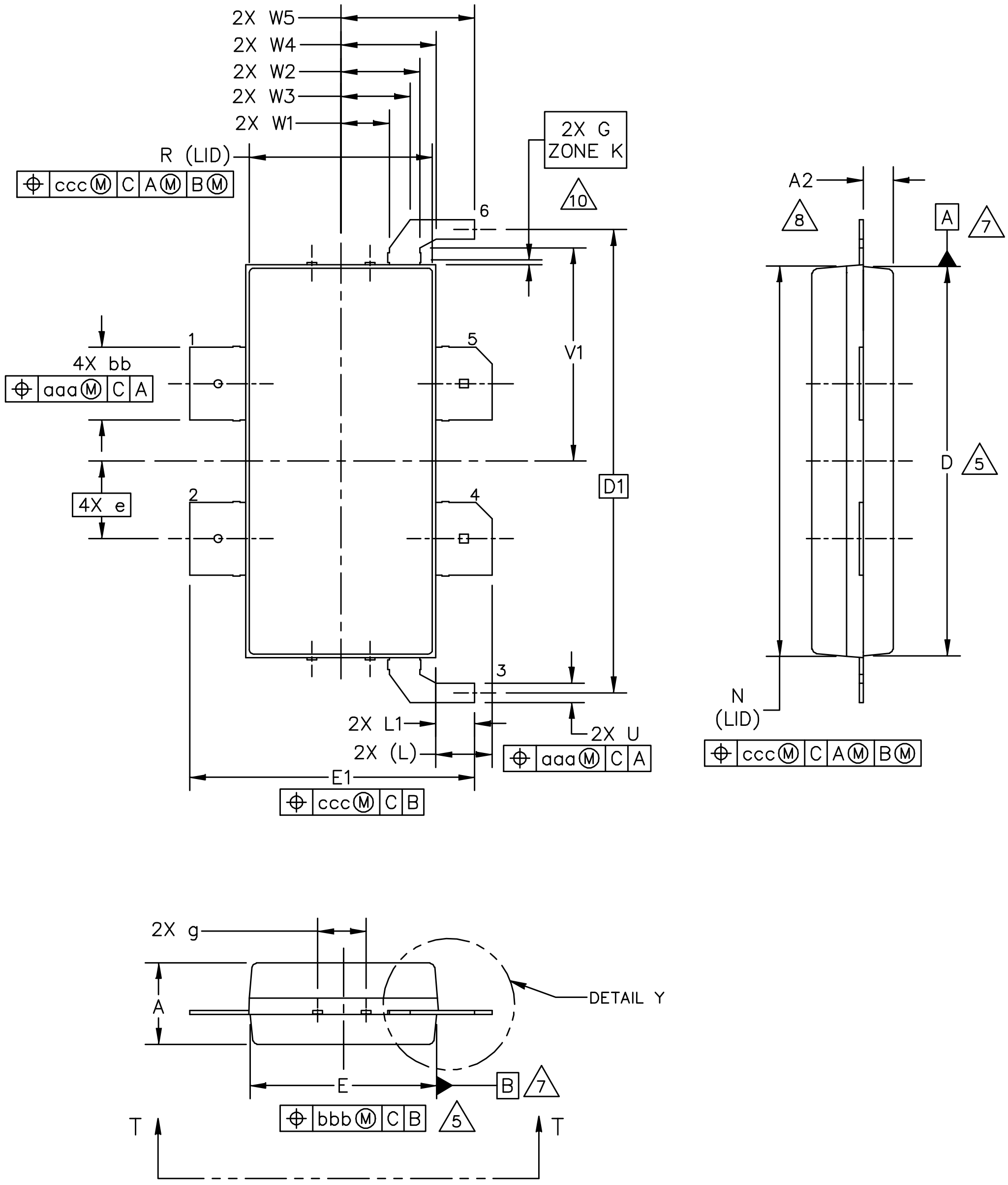
1 Package summary

Terminal position code	D (double)
Package type descriptive code	FM6F
Package style descriptive code	DFM (double-ended flange mount)
Mounting method type	T (through-hole mount)
Issue date	18-04-2019
Manufacturer package code	98ASA01355D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	20.4	-	mm
package width	-	9.8	-	mm
package height	-	4.26	-	mm
actual quantity of termination	-	6	-	

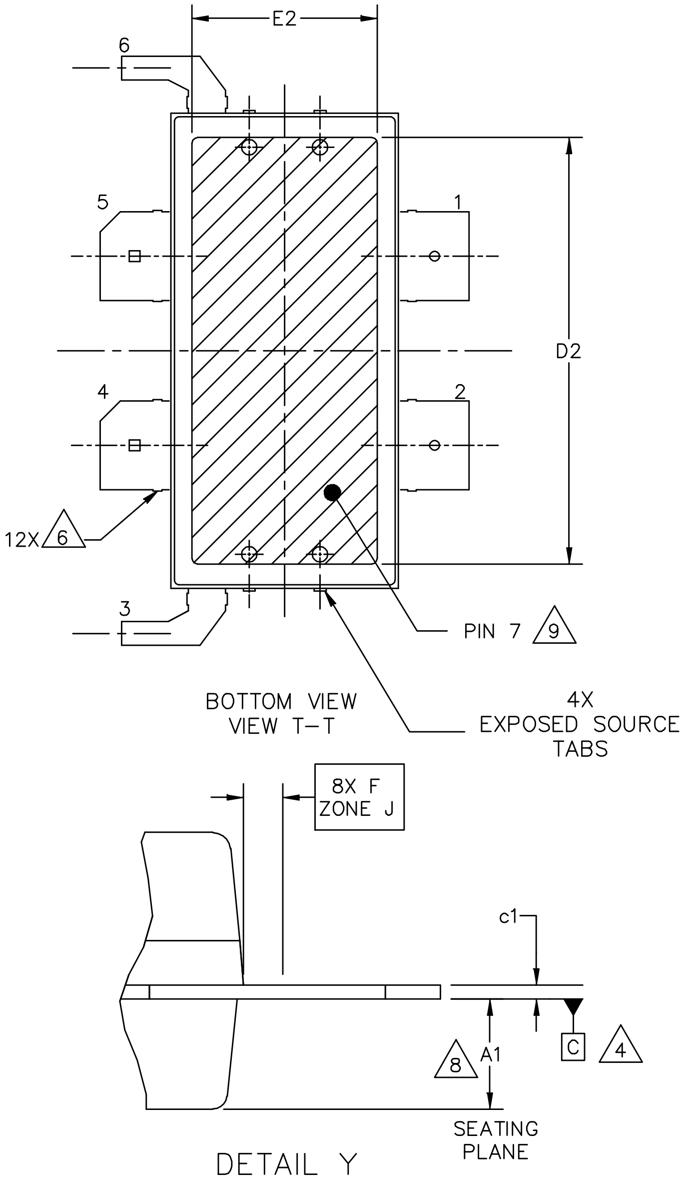
2 Package outline



DATE: 18 APR 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01355D	REVISION: O	

Figure 1. Package outline FM6F (SOT2005-1)



DATE: 18 APR 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01355D	REVISION: O	

Figure 2. Package outline detail FM6F (SOT2005-1)

NOTES:

1. CONTROLLING DIMENSION: INCH

2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M−1994.

3. UNLESS OTHERWISE SPECIFIED, ALL DIMENSIONS ARE SYMMETRICAL ABOUT CENTERLINES.

4. DATUM C IS LOCATED AT THE BOTTOM OF THE LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.

5. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS. ALLOWABLE PROTRUSION IS .006 INCH (0.15 MM) PER SIDE.

6. DIMENSION bb, W1, W2 DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION .005 INCH (0.13 MM).

7. DATUM A AND B TO BE DETERMINED AT DATUM PLANE C.

8. DIMENSIONS A1 AND A2 APPLY WITHIN ZONE J ONLY. A1 APPLIES TO PINS 1, 2, 4, AND 5. A2 APPLIES TO PINS 3 AND 6.

9. HATCHING REPRESENTS THE EXPOSED AREA OF THE HEAT SLUG. THE DIMENSIONS D2 AND E2 REPRESENT THE VALUES BETWEEN THE TWO OPPOSITE POINTS ALONG THE EDGES OF EXPOSED AREA OF HEAT SLUG.

10. ZONE K REPRESENTS NON−SOLDERABLE REGION WHERE MOLD FLASH AND RESIN BLEED ARE PERMITTED ON BOTH SIDES OF THE LEADS.

	INCH		MILLIMETER			INCH		MILLIMETER	
DIM	MIN	MAX	MIN	MAX	DIM	MIN	MAX	MIN	MAX
A	.158	.178	4.01	4.52	U	.035	.045	0.89	1.14
A1	.059	.065	1.55	1.60	V1	.430	.445	10.92	11.30
A2	.056	.068	1.42	1.73	W1	.095	.105	2.41	2.67
D	.800	.806	20.32	20.47	W2	.158	.168	4.01	4.27
D1	.956 BSC		24.28 BSC		W3	.138	.148	3.51	3.76
D2	.717	−−−	18.21	−−−	W4	.192	.202	4.88	5.13
E	.382	.388	9.70	9.86	W5	.435	.445	11.05	11.30
E1	.609	.619	15.47	15.72	bb	.147	.153	3.73	3.89
E2	.309	−−−	7.85	−−−	c1	.008	.010	0.20	0.25
F	.030 BSC		0.76 BSC		e	.160 BSC		4.06 BSC	
G	.010 BSC		0.25 BSC		g	.115	.125	2.92	3.18
(L)	.105	.125	2.67	3.18	aaa	.004		0.10	
L1	.074	.094	1.88	2.39	bbb	.006		0.15	
N	.765	.789	19.43	20.04	ccc	.010		0.25	
R	.373	.383	9.47	9.73					

DATE: 18 APR 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01355D	REVISION: O	

Figure 3. Package outline note FM6F (SOT2005-1)

3 Legal information

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